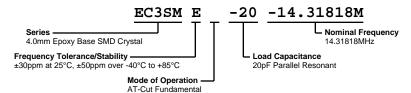
# EC3SME-20-14.31818M

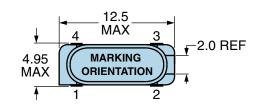


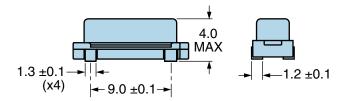


| ELECTRICAL SPECIFICATIONS     |  |  |
|-------------------------------|--|--|
| Nominal Frequency             | 14.31818MHz                                |  |
| Frequency Tolerance/Stability | ±30ppm at 25°C, ±50ppm over -40°C to +85°C |  |
| Aging at 25°C                 | ±5ppm/year Maximum                         |  |
| Load Capacitance              | 20pF Parallel Resonant                     |  |
| Shunt Capacitance (C0)        | 7pF Maximum                                |  |
| Equivalent Series Resistance  | 70 Ohms Maximum                            |  |
| Mode of Operation             | AT-Cut Fundamental                         |  |
| Drive Level                   | 1mWatts Maximum                            |  |
| Storage Temperature Range     | -40°C to +85°C                             |  |
| Insulation Resistance         | 500 Megaohms Minimum at 100Vdc             |  |

| ENVIRONMENTAL & MECHANICAL SPECIFICATIONS |                                      |  |
|---|--------------------------------------|--|
| Fine Leak Test                            | MIL-STD-883, Method 1014 Condition A |  |
| Gross Leak Test                           | MIL-STD-883, Method 1014 Condition C |  |
| Mechanical Shock                          | MIL-STD-202, Method 213 Condition C  |  |
| Resistance to Soldering Heat              | MIL-STD-202, Method 210              |  |
| Resistance to Solvents                    | MIL-STD-202, Method 215              |  |
| Solderability                             | MIL-STD-883, Method 2003             |  |
| Temperature Cycling                       | MIL-STD-883, Method 1010             |  |
| Vibration                                 | MIL-STD-883, Method 2007 Condition A |  |

### **MECHANICAL DIMENSIONS (all dimensions in millimeters)**





| PIN | CONNECTION         |
|-----|--------------------|
| 1   | Crystal            |
| 2   | Connected to Pin 3 |
| 3   | Connected to Pin 2 |
| 4   | Crystal            |

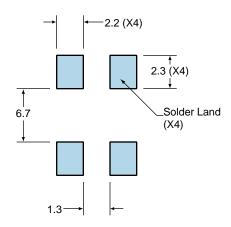
| LINE | MARKING                          |
|------|----------------------------------|
| 1    | E14.318<br>E=Ecliptek Designator |

# EC3SME-20-14.31818M



## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

## EC3SME-20-14.31818M



### **Recommended Solder Reflow Methods**



### Low Temperature Infrared/Convection 225°C

| T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate) | 5°C/second Maximum         |
|---|----------------------------|
| Preheat   |                            |
| - Temperature Minimum (T <sub>s</sub> MIN)          | N/A                        |
| - Temperature Typical (T <sub>s</sub> TYP)          | 150°C                      |
| - Temperature Maximum (T <sub>s</sub> MAX)          | N/A                        |
| - Time (t <sub>s</sub> MIN)                         | 30 - 60 Seconds            |
| Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )    | 5°C/second Maximum         |
| Time Maintained Above:                              |                            |
| - Temperature (T∟)                                  | 150°C                      |
| - Time (t∟)   | 200 Seconds Maximum        |
| Peak Temperature (T <sub>P</sub> )                  | 225°C Maximum              |
| Target Peak Temperature (T <sub>P</sub> Target)     | 225°C Maximum 2 Times      |
| Time within 5°C of actual peak (tp)                 | 80 seconds Maximum 2 Times |
| Ramp-down Rate                                      | 5°C/second Maximum         |
| Time 25°C to Peak Temperature (t)                   | N/A                        |
| Moisture Sensitivity Level                          | Level 1                    |

#### **Low Temperature Manual Soldering**

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

#### **High Temperature Manual Soldering**

260°C Maximum for 5 seconds Maximum, 2 times Maximum.